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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10015276	FILING DATE 12/11/2001	CLASS 438	SUBCLASS 14	GAU 2842	EXAMINER PERT
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**APPLICANTS: Hosoya Naoki; Takagi Yuuji; Shibuya Hisae; Obara Kenji;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO	
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no	16869P-036200US	
Verified and Acknowledged Examiner's initials			
TITLE : Method and apparatus for inspecting defects in a semiconductor wafer			
U.S.DEP'T. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
PREPARED FOR ISSUE				
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